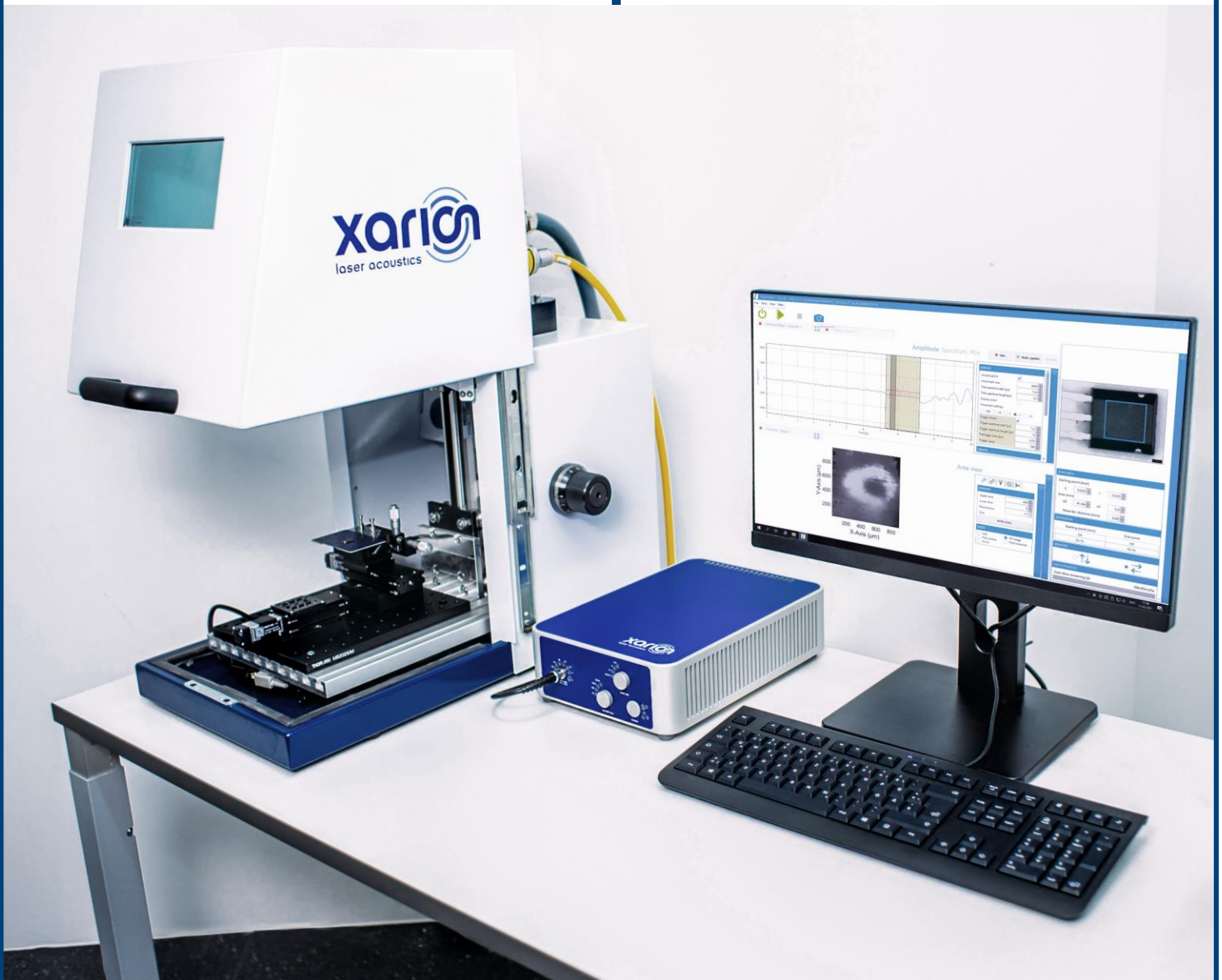


Non-contact

# Ultrasonic Inspection Tool



# Functionality

XARION's unique laser-based technology enables the ultrasonic inspection of semiconductor components without any coupling liquid. The sensor technology is integrated into a stand-alone desktop tool offering two operation modes: a high-speed non-contact imaging mode, and an ultrafast single-shot evaluation mode for up to 1000 components per second. Both modes allow for the nondestructive detection of delaminations and other internal defects. XARION's technology increases productivity in failure analysis and reliability in production.

## Features

- Compact and highly versatile desktop tool for ultrasonic inspection of semiconductor components
- Unique non-contact sensor technology without liquid coupling media
- High-speed imaging mode with up to 10 000 imaging points / second
- Single-shot inspection mode for up to 1000 components / second



Contact:  
Dr. Matthias Brauns  
m.brauns@xarion.com  
+43 1 9076076 23

